

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

FDS4435A-MS

Product specification

Features

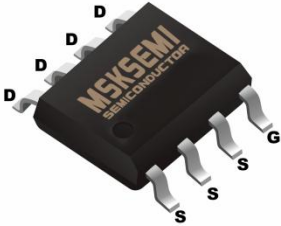
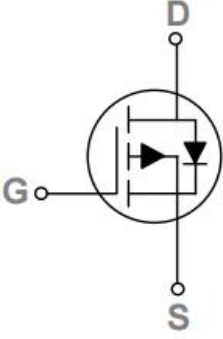

- -30V,-9A, RDS(ON) =16mΩ@VGS = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

Application

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

BVDSS	RDSON	ID
-30V	16mΩ	-9A

Reference News

PACKAGE OUTLINE	Pin Configuration	Marking
 <p>SOP-8</p>		

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current - Continuous (T _C =25°C)	-9	A
	Drain Current - Continuous (T _C =75°C)	-5.1	A
I _{DM}	Drain Current - Pulsed ¹	-27	A
P _D	Power Dissipation (T _C =25°C)	2.1	W
	Power Dissipation - Derate above 25°C	0.017	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 125	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	60	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	---	-0.03	---	V/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-30V , V _{GS} =0V , T _J =25°C	---	---	-1	uA
		V _{DS} =-24V , V _{GS} =0V , T _J =125°C	---	---	-10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±20V , V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V , I _D =-8A	---	16	22	mΩ
		V _{GS} =-4.5V , I _D =-5A	---	22	32	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.6	-2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	4	---	mV/°C
g _{fs}	Forward Transconductance	V _{DS} =-10V , I _D =-3A	---	6.8	---	S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{2, 3}	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-5A	---	11	---	nC
Q _{gs}	Gate-Source Charge ^{2, 3}		---	3.4	---	
Q _{gd}	Gate-Drain Charge ^{2, 3}		---	4.2	---	
T _{d(on)}	Turn-On Delay Time ^{2, 3}	V _{DD} =-15V , V _{GS} =-10V , R _G =6Ω I _D =-1A	---	5.8	---	ns
T _r	Rise Time ^{2, 3}		---	18.8	---	
T _{d(off)}	Turn-Off Delay Time ^{2, 3}		---	46.9	---	
T _f	Fall Time ^{2, 3}		---	12.3	---	
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , F=1MHz	---	1250	---	pF
C _{oss}	Output Capacitance		---	160	---	
C _{rss}	Reverse Transfer Capacitance		---	90	---	

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _s	Continuous Source Current	V _G =V _D =0V , Force Current	---	---	-9	A
I _{SM}	Pulsed Source Current		---	---	-16	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _s =-1A , T _J =25°C	---	---	-1.3	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

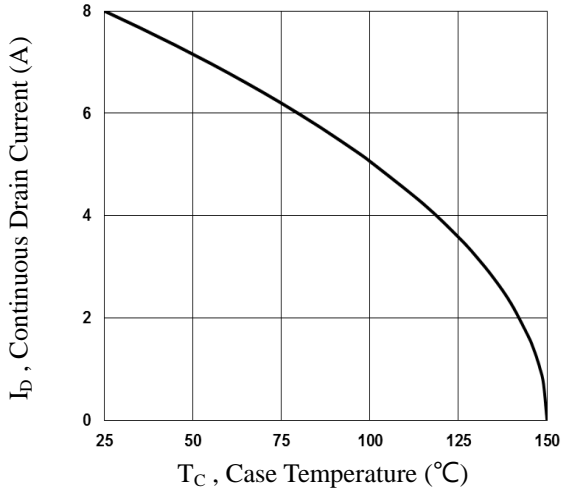


Fig.1 Continuous Drain Current vs. T_c

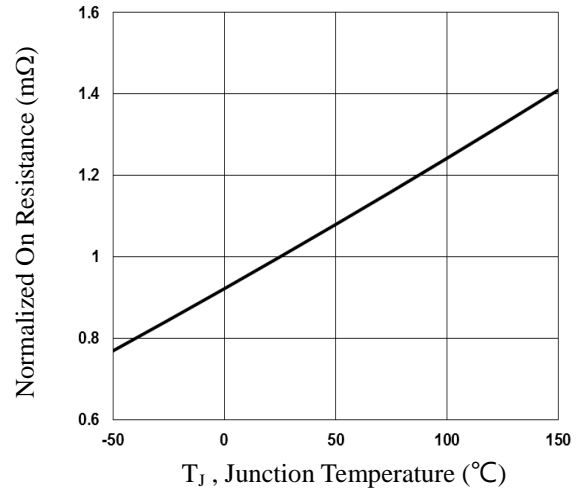


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

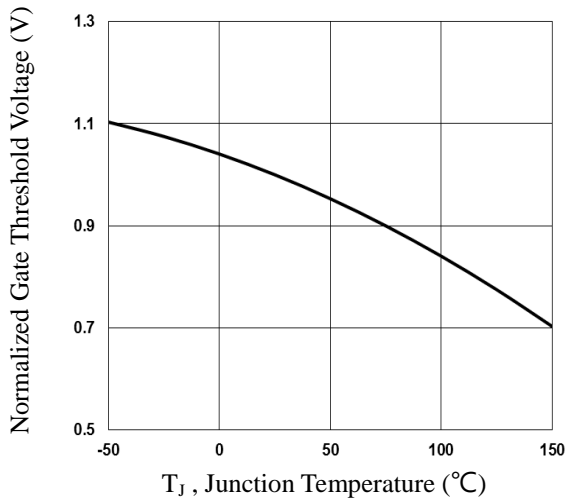


Fig.3 Normalized V_{th} vs. T_j

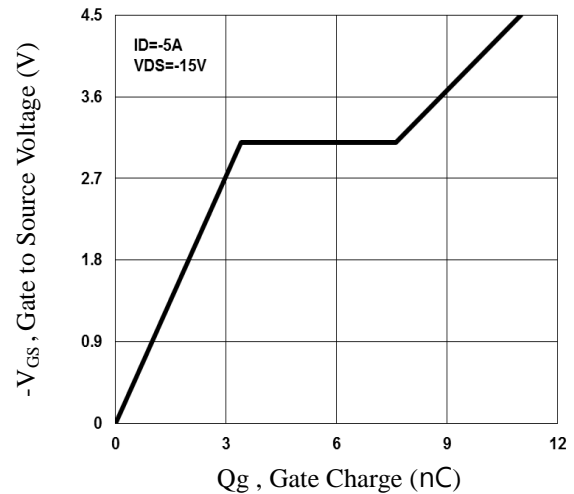


Fig.4 Gate Charge Waveform

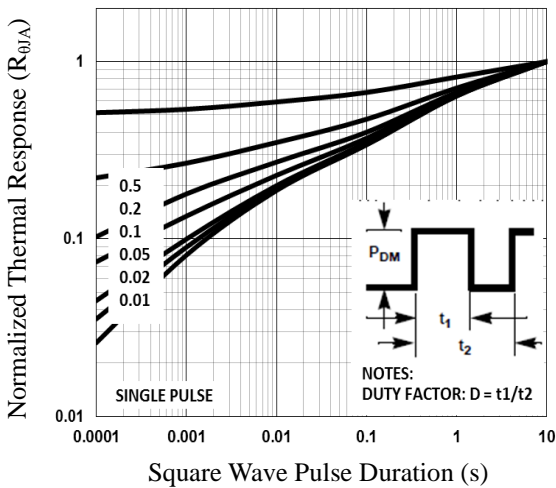


Fig.5 Normalized Transient Impedance

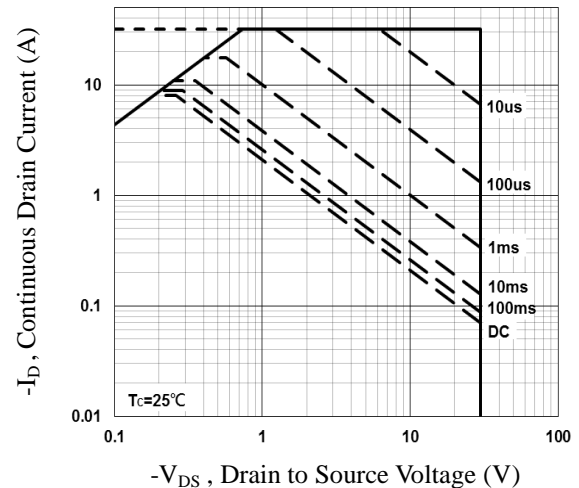


Fig.6 Maximum Safe Operation Area

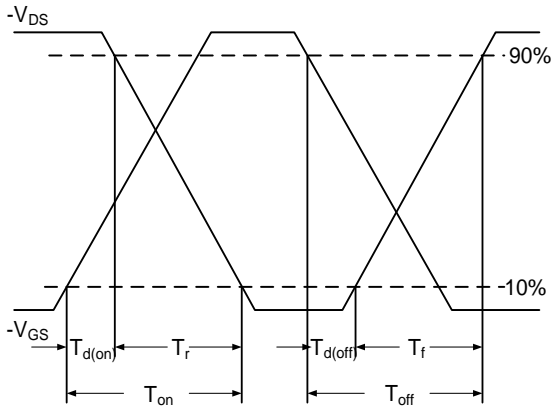


Fig.7 Switching Time Waveform

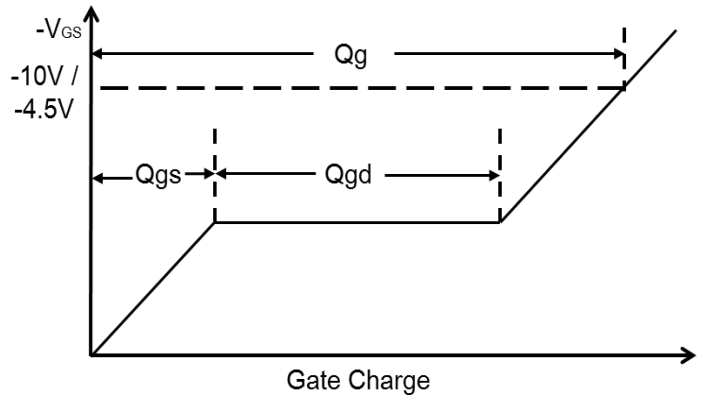
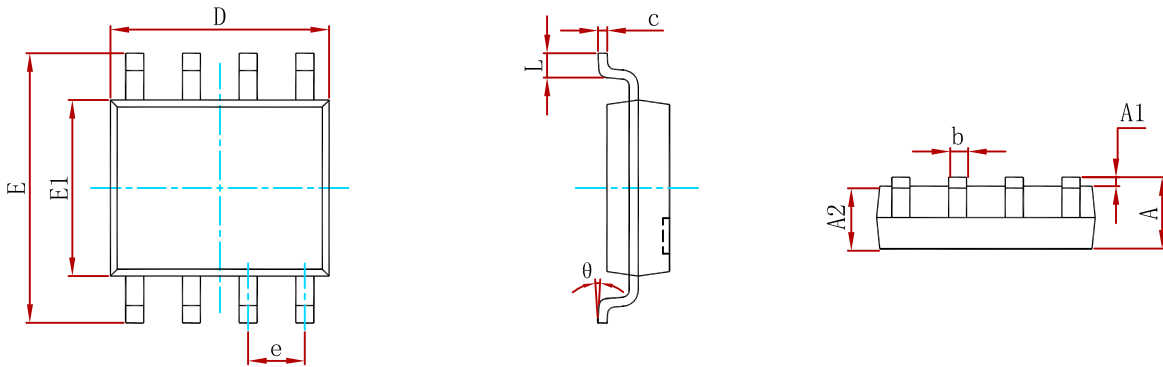


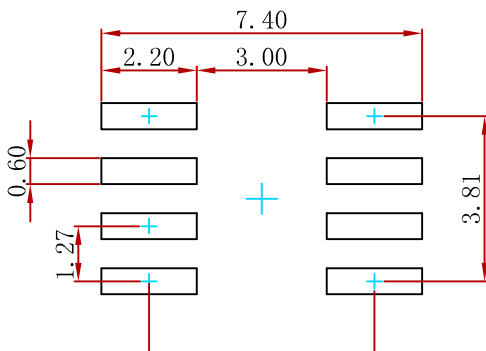
Fig.8 Gate Charge Waveform

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
theta	0°	8°	0°	8°

Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
FDS4435A-MS	SOP-8	3000

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